



SEMICONDUCTOR Small Signal Products

MATERIAL CONTENT LIST

PACKAGE
FAMILY:
DATE:
REVISION:

SOD-57

1-Dec-2020

10



HALOGEN
FREE

RoHS
COMPLIANT



MATERIAL CONTENT					
Part	Material	CAS N°	weight mg	% of weight	ppm of total weight
Leads	Cu	7440-50-8	185.0	58.7%	499585
	Fe	7439-89-6	70.2	22.3%	189701
	Mo	7439-98-7	58.8	18.7%	158804
	Ag	7440-22-4	0.32	0.1%	864
	C	7440-44-0	0.32	0.1%	864
	O ₂	7782-44-7	0.32	0.1%	864
	TOTAL			315.0	
Terminal finish	Sn	7440-31-5	3.0	96.5%	8075
	Ag	7440-22-4	0.11	3.5%	297
	TOTAL		3.10		
Package Glass	PbO *)	1317-36-8	21.5	42.0%	57931
	SiO ₂	14808-60-7	19.4	38.0%	52395
	B ₂ O ₃	1303-86-2	7.7	15.0%	20688
	Al ₂ O ₃	1344-28-1	2.6	5.0%	6887
	TOTAL		51.1		
Silicon Chip Chip Metal	Si	7440-21-3	1.00	90.0%	2698
	Al	7429-90-5	0.11	10.0%	300
	TOTAL		1.11		
Ink	Carbon black	1333-86-4	0.0057	33.4%	15
	Phenol	108-95-2	0.0009	5.0%	2
	Tributyl phosphate	126-73-8	0.0105	61.5%	28
	TOTAL		0.02		
Total weight			370		

Remarks: Total weight range $\pm 10\%$

*) Pb in glass of electronic components acc. RoHS exempted; Lead Monoxide just raw ingredient for glass production, but not present as such in glass anymore

**) Not detected

Wave Soldering acc. CECC00802

Material Analyses Reports available on request